



P-Channel Enhancement-Mode Vertical DMOS FETs

Ordering Information

BV _{DSS} /	R _{DS(ON)}	I _{D(ON)}	Order Number / Package		
BV _{DGS}	, ,	, ,	TO-92		
-500V	125Ω	-100mA	VP0550N3		

Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{iss} and fast switching speeds
- Excellent thermal stability
- Integral Source-Drain diode
- High input impedance and high gain
- Complementary N- and P-channel devices

Applications

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- ☐ Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Absolute Maximum Ratings

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

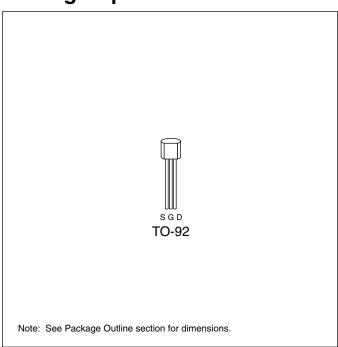
^{*} Distance of 1.6 mm from case for 10 seconds.

Advanced DMOS Technology

These enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Option



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Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _C = 25°C	$ heta_{ extsf{jc}}$ $^{\circ}$ C/W	$ heta_{ja}$ °C/W	I _{DR} *	I _{DRM}
TO-92	-54mA	-0.25A	1W	125	170	-54mA	-0.25A

^{*} I_D (continuous) is limited by max rated T_i .

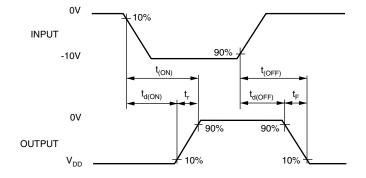
Electrical Characteristics (@ 25°C unless otherwise specified)

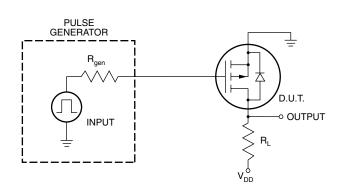
Symbol	Parameter	Min	Тур	Max	Unit	Conditions	
BV_{DSS}	Drain-to-Source Breakdown Voltage	-500			V	$V_{GS} = 0V$, $I_D = -1mA$	
V _{GS(th)}	Gate Threshold Voltage	-2.0		-4.5	V	$V_{GS} = V_{DS}, I_D = -1mA$	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with Temperature		3.5	6	mV/°C	$V_{GS} = V_{DS}, I_D = -1 \text{mA}$	
I _{GSS}	Gate Body Leakage			-100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
I _{DSS}	Zero Gate Voltage Drain Current			-10		$V_{GS} = 0V$, $V_{DS} = Max$ Rating	
				-1000	μΑ	$V_{GS} = 0V$, $V_{DS} = 0.8$ Max Rating $T_A = 125^{\circ}C$	
I _{D(ON)}	ON-State Drain Current		-90		mA	$V_{GS} = -5V, V_{DS} = -25V$	
		-100	-240		-	$V_{GS} = -10V, V_{DS} = -25V$	
R _{DS(ON)}	Static Drain-to-Source ON-State Resistance		85		Ω	$V_{GS} = -5V$, $I_D = -5mA$	
			80	125		$V_{GS} = -10V, I_{D} = -10mA$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with Temperature		0.85		%/°C	$V_{GS} = -10V, I_D = -10mA$	
G _{FS}	Forward Transconductance	25	40		mʊ	$V_{DS} = -25V, I_{D} = -10mA$	
C _{ISS}	Input Capacitance		40	70		V 0V V 05V	
C _{oss}	Common Source Output Capacitance		10	20	pF	$V_{GS} = 0V, V_{DS} = -25V$ f = 1 MHz	
C _{RSS}	Reverse Transfer Capacitance		3	10			
t _{d(ON)}	Turn-ON Delay Time		5	10		V _{DD} = -25V	
t _r	Rise Time		8	10	ns	$I_D = -100 \text{mA}$ $R_{GEN} = 25 \Omega$	
t _{d(OFF)}	Turn-OFF Delay Time		8	15			
t _f	Fall Time		5	16			
V _{SD}	Diode Forward Voltage Drop		-0.8	-1.5	V	$V_{GS} = 0V, I_{SD} = -0.1A$	
t _{rr}	Reverse Recovery Time		200		ns	$V_{GS} = 0V, I_{SD} = -0.1A$	

Notes:

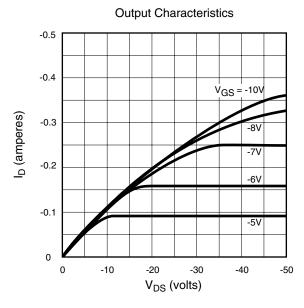
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: $300\mu s$ pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

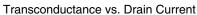
Switching Waveforms and Test Circuit

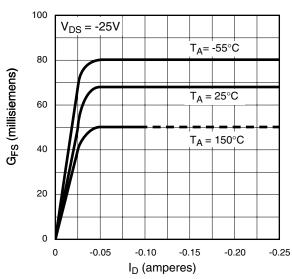




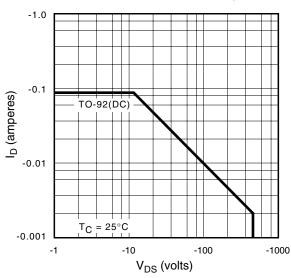
Typical Performance Curves



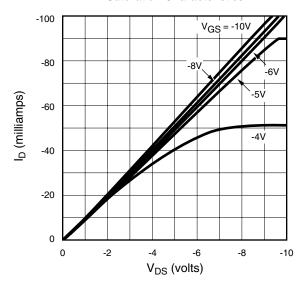




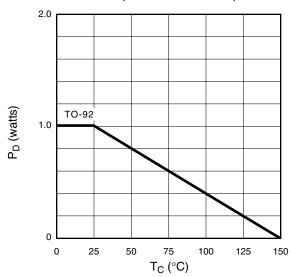
Maximum Rated Safe Operating Area



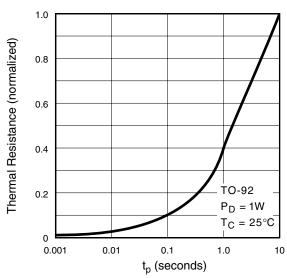
Saturation Characteristics



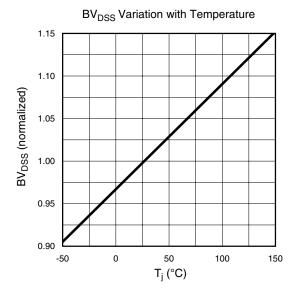
Power Dissipation vs. Case Temperature

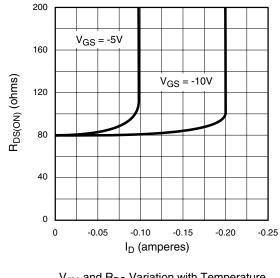


Thermal Response Characteristics

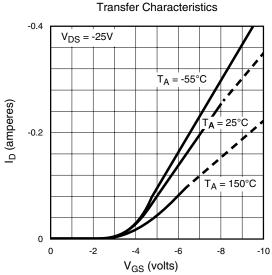


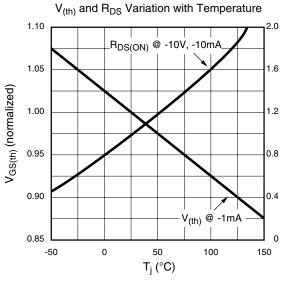
Typical Performance Curves

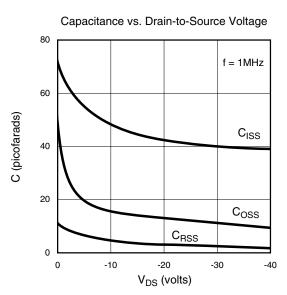


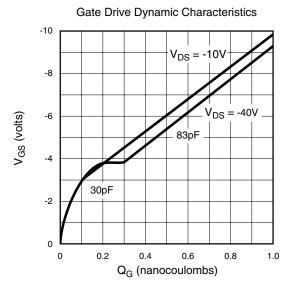


On-Resistance vs. Drain Current









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R_{DS(ON)} (normalized)

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.